

PATENT APPLICATION
Attorney Docket: 54364

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Gupta, et al.	
Serial No.:	09/847,667	
Filed:	5/1/2001	
For:	Method for Bonding Wafers to Produce Stacked Integrated Circuits	
Group Art Unit:	2827	Examiner: James Mitchell

RESPONSE TO OFFICE ACTION

Hon. Commissioner of Patents
and Trademarks
Washington, D.C. 20231

Sir:

In reply to the Office Action dated 1/17/03, in the above-identified patent application, Applicant submits the following Remarks. The period for response to this office action having been extended by three months by the accompanying petition for extension of time. Applicant respectfully requests that the Examiner reconsider the grounds for rejection stated in the Office Action.